PCN Number: 20210608000.2		PCN Date: July 8, 2021
Title: Bubble Wrap removal for Select MSL1 Devices		
Customer Contact: PCN Manager Dept: Quality Services		
Proposed 1 st Ship Date: Jan	Estimated	
Change Type:	711411	request
Assembly Site	Design	Wafer Bump Site
Assembly Process	Data Sheet	Wafer Bump Material
Assembly Materials	Part number change	Wafer Bump Process
Mechanical Specification	Test Site	Wafer Fab Site
Packing/Shipping/Labeling	Test Process	Wafer Fab Materials
		☐ Wafer Fab Process
PCN Details		
Description of Change:		
This change notification is to an in the "Product Affected" Section		val for select MSL1 devices listed To
Packing Description	With Bubble Wrap	Without Bubble Wrap
Visual comparison		SERVINE DODY
Reason for Change:		
Continuity of supply.		
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):		
None		
Anticipated impact on Mater	ial Declaration	
No Impact to the Material Declaration	Material Declarations or Prod from production data and will production release. Upon pro reports can be obtained at th	duction release the revised
Changes to product identification resulting from this PCN:		
None		•••
Product Affected:		
CAXC8T245QRHLRQ1 CLXC8	BT245QRHLRQ1	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
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Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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